

TOREX SEMICONDUCTOR LTD.
Quality Assurance Dept.

Composition Table

Product(Pb-free): XC6216Bxxx8R-G
Typical Mass: 2.3 mg

Part name	Weight(mg)	Material name	Ratio(ppm)	CAS number
Silicon chip	0.308	Silicon	134000	7440-21-3
Lead pad	0.645	Nickel	280600	7440-02-0
	0.061	Silver	26700	7440-22-4
	0.007	Gold	3100	7440-57-5
Die attach	0.002	Silica	1000	60676-86-0
	0.001	Epoxy Resin	500	—
	0.001	Phenol Resin	300	—
	0.001	Acrylic Resin	300	—
Bonding wire	0.030	Gold	13200	7440-57-5
Resin	1.149	Silica	499800	60676-86-0
	0.093	Epoxy Resin	40500	—

* The component composition is based on the information provided by raw material vender.

* The mass of the IC and its fractions could be different due to the manufacturing conditions of materials.

* Any indication "-" in CAS number means "confidential."